

(1,00 mm) .0394"

SAL1-120-01-S-S-A-TR

SAL1-140-01-S-S-A-TR

SAL1-127-01-S-S-A-TR

SAL1 SERIES

HIGH SPEED MICRO PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SAL1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Au or Sn over

50µ" (1,27 µm) Ni

Operating Temp:

-55°C to +125°C

Current Rating:

1.9 A per pin

(2 adjacent pins powered)

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max

Mates with:

(1,60 mm) .062" or

(2,40 mm) .093" card

Mount in pairs on same side or opposite sides for easy signal routing

Surface Mount

Variable mating card thickness

Weld tab

Large deflection BeCu contact

SAL1		Rated @ 3dB Insertion Loss*
Single-Ended Signaling	Top or Bottom	8.5 GHz / 17 Gbps
Differential Pair Signaling	Top	9 GHz / 18 Gbps
Differential Pair Signaling	Bottom	10 GHz / 20 Gbps

*Performance data includes effects of a non-optimized PCB.
Complete test data available at www.samtec.com?SAL1 or contact sig@samtec.com

SATALink™
Compatible

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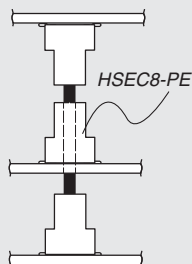
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

OTHER SOLUTIONS



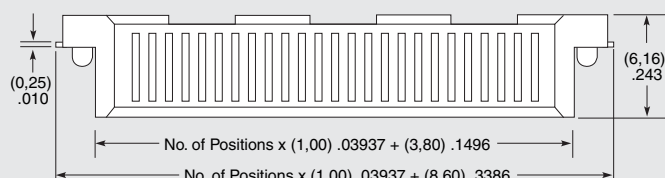
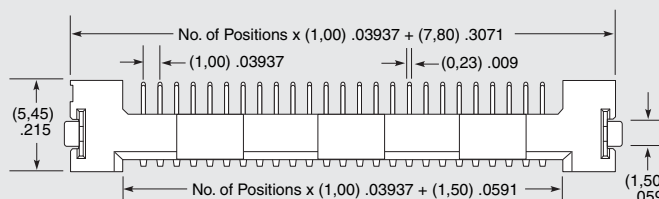
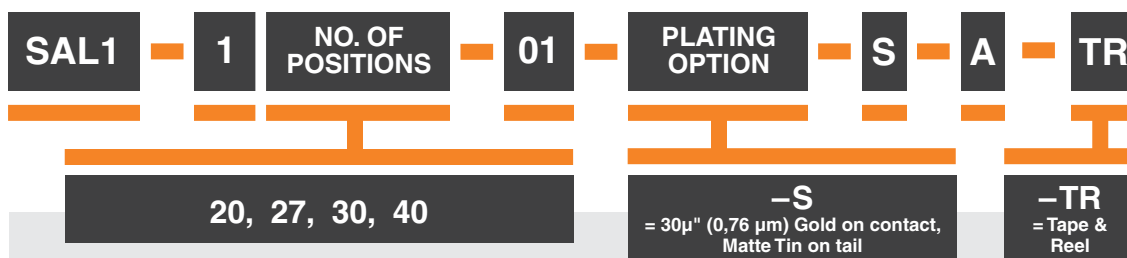
- Card pass-through option. See HSEC8-PE Series.

ALSO AVAILABLE (MOQ Required)

- Heavy Gold plating Contact Samtec.

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Note: Some lengths, styles and options are non-standard, non-returnable.



APPLICATIONS

